



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	02/17/2015
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HSLV*I82R01G	A	SH1A	02/17/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
4400.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75X20.15X5.15	3	Through-hole	
Comment	Package: DO 247; MD valid for STTH6012W			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HSLV*182R01G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	25.302	mg	supplier	die	Silicon (Si)	7440-21-3		24.276	mg	959450	5517
				supplier	metallization	Aluminium (Al)	7429-90-5		0.603	mg	23832	137
				supplier	passivation	Gamma-butyrolactone	96-48-0		0.141	mg	5573	32
						Polyhydroxyamide	55295-98-2		0.063	mg	2490	14
						Alcoxysilane	proprietary		0.004	mg	158	1
						Aryl Silicic Acid	proprietary		0.002	mg	79	0
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.012	mg	474	3
						Gold (Au)	7440-57-5		0.035	mg	1383	8
Leadframe	Copper & Its alloys	2690.549	mg	supplier	alloy	Nickel (Ni)	7440-02-0		0.166	mg	6561	38
						Copper (Cu)	7440-50-8		2686.065	mg	998333	610469
						Iron (Fe)	7439-89-6		1.237	mg	460	281
						Iron Phosphide (Fe2P)	1310-43-6		2.259	mg	840	513
				supplier	metallization	Nickel (Ni)	7440-02-0		0.914	mg	340	208
Soft solder	Other organic materials	15.755	mg	JIG R	solder	Phosphorus (P)	12185-10-3		0.074	mg	28	17
						Lead (Pb)	7439-92-1	7a-Lead in high me	15.046	mg	954998	3420
						Silver (Ag)	7440-22-4		0.394	mg	25008	90
Bonding wire	Other inorganic materials	8.171	mg	supplier	wire	Tin (Sn)	7440-31-5		0.315	mg	19994	72
						Aluminium (Al)	7429-90-5		8.171	mg	1000000	1857
encapsulation	Other organic materials	1654.026	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1439.002	mg	870000	327046
						Epoxy resin	proprietary		165.403	mg	100000	37592
						Phenol resin	proprietary		41.351	mg	25000	9398
						Carbon Black	1333-86-4		8.27	mg	5000	1880
connections coating	Solder	6.197	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.197	mg	1000000	1408